SN54HC574, SN74HC574 OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

SCLS148F - DECEMBER 1982 - REVISED AUGUST 2003

- Wide Operating Voltage Range of 2 V to 6 V
- High-Current 3-State Noninverting Outputs Drive Bus Lines Directly or Up To 15 LSTTL Loads
- Low Power Consumption, 80-μA Max I_{CC}
- Typical t_{pd} = 22 ns
- ±6-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Bus-Structured Pinout

description/ordering information

These octal edge-triggered D-type flip-flops feature 3-state outputs designed specifically for bus driving. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

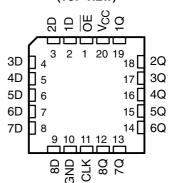
The eight flip-flops enter data on the low-to-high transition of the clock (CLK) input.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

SN54HC574 J OR W PACKAGE	
SN74HC574DB, DW, N, NS, OR PW PACKAG	iΕ
(TOP VIEW)	

	(101	·,	
ŌĒ	d 1	J ₂₀]v _{cc}
1D		19] 1Q
2D	[] 3	18] 2Q
3D	4	17] 3Q
4D	5	16] 4Q
5D	6	15] 5Q
6D	[7	14] 6Q
7D	8]	13] 7Q
8D	9	12] 8Q
GND	10	11] CLK
	-		

SN54HC574 . . . FK PACKAGE (TOP VIEW)



T _A	PACK	AGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING								
	PDIP – N	Tube of 20	SN74HC574N	SN74HC574N								
		Tube of 25	SN74HC574DW	110574								
	SOIC – DW	Reel of 2000	SN74HC574DWR	HC574								
1000 10 0500	SSOP – DB	Reel of 2000	SN74HC574DBR	HC574								
–40°C to 85°C	SOP – NS	Reel of 2000	SN74HC574NSR	HC574								
		Tube of 70	SN74HC574PW									
	TSSOP – PW	Reel of 2000	SN74HC574PWR	HC574								
		Reel of 250	SN74HC574PWT									
	CDIP – J	Tube of 20	SNJ54HC574J	SNJ54HC574J								
–55°C to 125°C	CFP – W	Tube of 85	SNJ54HC574W	SNJ54HC574W								
	LCCC – FK	Tube of 55	SNJ54HC574FK	SNJ54HC574FK								

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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SN54HC574, SN74HC574 OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

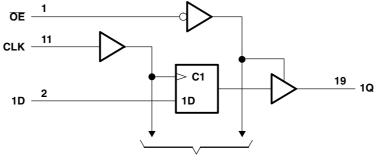
SCLS148F - DECEMBER 1982 - REVISED AUGUST 2003

description/ordering information (continued)

OE does not affect the internal operations of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

	FUNCTION TABLE (each flip-flop)												
	INPUTS	OUTPUT											
ŌE	CLK	D	Q										
L	\uparrow	Н	Н										
L	\uparrow	L	L										
L	H or L	Х	Q ₀										
Н	Х	Х	Z										

logic diagram (positive logic)



To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	±20 mA
Output clamp current, I_{OK} (V _O < 0 or V _O > V _{CC}) (see Note 1)	±20 mA
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$	±35 mA
Continuous current through V _{CC} or GND	±70 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package	70°C/W
DW package	58°C/W
N package	69°C/W
NS package	60°C/W
PW package	83°C/W
Storage temperature range, T _{stg} 65	°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



SN54HC574, SN74HC574 OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS

WITH 3-STATE OUTPUTS SCLS148F - DECEMBER 1982 - REVISED AUGUST 2003

recommended operating conditions (see Note 3)

			SI	154HC57	′ 4	SN74HC574			
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage		2	5	6	2	5	6	V
		$V_{CC} = 2 V$	1.5			1.5			
V _{IH} High-level	High-level input voltage	$V_{CC} = 4.5 V$	3.15			3.15			V
		$V_{CC} = 6 V$	4.2			4.2			
	Low-level input voltage	V _{CC} = 2 V			0.5			0.5	
V _{IL}		V _{CC} = 4.5 V			1.35			1.35	V
		$V_{CC} = 6 V$			1.8			1.8	
VI	Input voltage		0		V_{CC}	0		V_{CC}	V
Vo	Output voltage		0		V_{CC}	0		V_{CC}	V
		V _{CC} = 2 V			1000			1000	
Δt/Δv	Input transition rise/fall time	V _{CC} = 4.5 V			500			500	ns
		$V_{CC} = 6 V$			400			400	
T _A	Operating free-air temperature	-	-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	TEST CONDITIONS			Т	A = 25°C	;	SN54H	IC574	SN74H	C574	
PARAMETER	TEST CO	DNDITIONS	V _{CC}	MIN	ТҮР	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	1.9	1.998		1.9		1.9		
		I _{OH} = -20 μA	4.5 V	4.4	4.499		4.4		4.4		
V _{OH}	$V_i = V_{iH} \text{ or } V_{iL}$		6 V	5.9	5.999		5.9		5.9		V
		$I_{OH} = -6 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
		I _{OH} = -7.8 mA	6 V	5.48	5.8		5.2		5.34		
			2 V		0.002	0.1		0.1		0.1	
		l _{OL} = 20 μA	4.5 V		0.001	0.1		0.1		0.1	
V _{OL}	$V_{I} = V_{IH} \text{ or } V_{IL}$		6 V		0.001	0.1		0.1		0.1	V
		$I_{OL} = 6 \text{ mA}$	4.5 V		0.17	0.26		0.4		0.33	
		I _{OL} = 7.8 mA	6 V		0.15	0.26		0.4		0.33	
l _l	$V_{I} = V_{CC} \text{ or } 0$		6 V		±0.1	±100		±1000		±1000	nA
I _{OZ}	$V_{O} = V_{CC} \text{ or } 0$		6 V		±0.01	±0.5		±10		±5	μA
I _{CC}	$V_{I} = V_{CC} \text{ or } 0,$	l _O = 0	6 V			8		160		80	μA
Ci			2 V to 6 V		3	10		10		10	pF



SN54HC574, SN74HC574 **OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS** WITH 3-STATE OUTPUTS

SCLS148F - DECEMBER 1982 - REVISED AUGUST 2003

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

		N	T _A = 2	25°C	SN54H	IC574	SN74HC574		
		v _{cc}	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
		2 V		6		4		5	
f _{clock}	Clock frequency	4.5 V		30		20		24	MHz
		6 V		38		24		28	
	Pulse duration, CLK high or low	2 V	80		120		100		
tw		4.5 V	16		24		20		ns
		6 V	14		20		17		
		2 V	100		150		125		
t _{su}	Setup time, data before CLK↑	4.5 V	20		30		25		ns
		6 V	17		26		21		
	Hold time, data after CLK↑	2 V	5		5		5		ns
t _h		4.5 V	5		5		5		
		6 V	5		5		5		

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

	FROM	то		T	_A = 25°C	;	SN54H	IC574	SN74H	C574	
PARAMETER	(INPUT)	(OUTPUT)	v _{cc}	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	6	11		4		5		
f _{max}			4.5 V	30	36		20		24		MHz
			6 V	36	40		24		28		
			2 V		90	180		270		225	
t _{pd}	t _{nd} CLK	Any Q	4.5 V		28	36		54		45	ns
			6 V		24	31		46		38	
			2 V		77	150		225		190	
t _{en}	ŌĒ	Any Q	4.5 V		26	30		45		38	38 ns
			6 V		23	26		38		32	
			2 V		52	150		225		190	
t _{dis}	ŌE	Any Q	4.5 V		24	30		45		38	ns
			6 V		22	26		38		32	
			2 V		28	60		90		75	
tt		Any Q	4.5 V		8	12		18		15	ns
			6 V		6	10		15		13	



SN54HC574, SN74HC574 **OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS** WITH 3-STATE OUTPUTS SCLS148F – DECEMBER 1982 – REVISED AUGUST 2003

switching characteristics over recommended operating free-air temperature range, $C_L = 150 \text{ pF}$ (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	v	Т	₄ = 25°C	;	SN54H	IC574	SN74H	C574	
PARAMETER	(INPUT)	(OUTPUT)	v _{cc}	MIN	ТҮР	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	6					5		
f _{max}			4.5 V	30					24		MHz
			6 V	36					28		
			2 V		105	265		400		330	
t _{pd}	CLK	CLK Any Q	4.5 V		36	53		80		66	ns
			6 V		31	46		68		57	
			2 V		95	235		355		295	
t _{en}	OE	Any Q	4.5 V		32	47		71		59	ns
			6 V		28	41		60		51	
			2 V		60	210		315		265	
tt		Any Q	4.5 V		17	42		63		53	ns
			6 V		14	36		53		45	

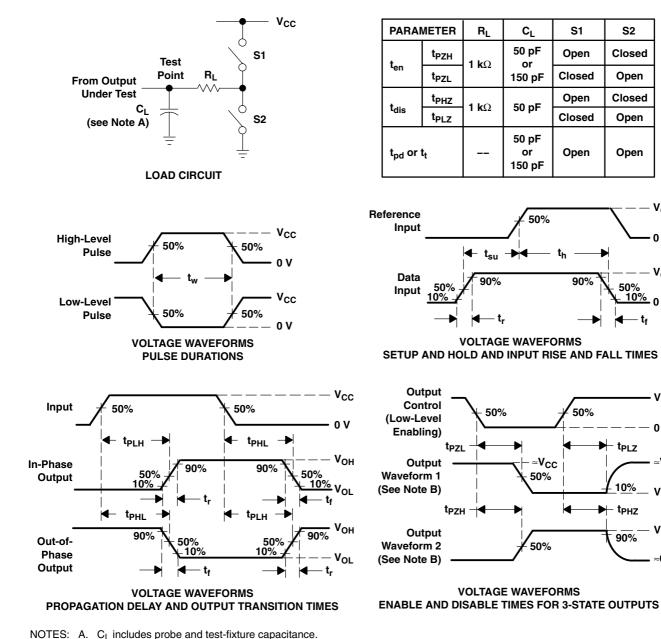
operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	ТҮР	UNIT
C _{pd}	Power dissipation capacitance per flip-flop	No load	100	pF



SN54HC574, SN74HC574 OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

SCLS148F - DECEMBER 1982 - REVISED AUGUST 2003



PARAMETER MEASUREMENT INFORMATION

CL

50 pF

or

150 pF

50 pF

50 pF

or 150 pF

50%

t_h

90%

50%

≈V_{CC}

50%

50%

S1

Open

Closed

Open

Closed

Open

S2

Closed

Open

Closed

Open

Open

50%

t_{PLZ}

10%

t_{PHZ}

90%

10%

 v_{cc}

0 V

V_{CC}

0 V

Vcc

0 V

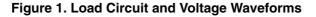
≈V_{CC}

VOL

VOH

≈0 V

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_r = 6 ns, t_f = 6 ns.
- D. For clock inputs, f_{max} is measured when the input duty cycle is 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
- G. t_{PZL} and t_{PZH} are the same as t_{en}.
- H. t_{PLH} and t_{PHL} are the same as t_{pd} .







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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp	Samples (Requires Login)
JM38510/65604BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	
M38510/65604BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	
SN54HC574J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	
SN74HC574DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC574DBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC574DBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC574DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC574DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC574DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC574DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC574DWRE4	OBSOLET	SOIC	DW	20		TBD	Call TI	Call TI	
SN74HC574N	ACTIVE	PDIP	Ν	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74HC574N3	OBSOLET	E PDIP	Ν	20		TBD	Call TI	Call TI	
SN74HC574NE4	ACTIVE	PDIP	Ν	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74HC574NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC574NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC574PW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC574PWE4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC574PWG4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	



23-Dec-2012

Orderable Device	Status	Package Type	Package	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Samples
	(1)		Drawing			(2)		(3)	(Requires Login)
SN74HC574PWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC574PWRE4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC574PWRG3	PREVIEW	TSSOP	PW	20	2000	TBD	Call TI	Call TI	
SN74HC574PWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC574PWT	ACTIVE	TSSOP	PW	20	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC574PWTE4	ACTIVE	TSSOP	PW	20	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC574PWTG4	ACTIVE	TSSOP	PW	20	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SNJ54HC574FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54HC574J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	
SNJ54HC574W	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54HC574, SN74HC574 :

Catalog: SN74HC574

• Military: SN54HC574

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

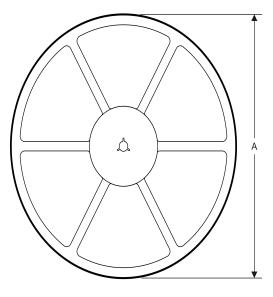
PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION

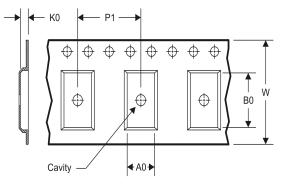
REEL DIMENSIONS

TEXAS INSTRUMENTS





TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

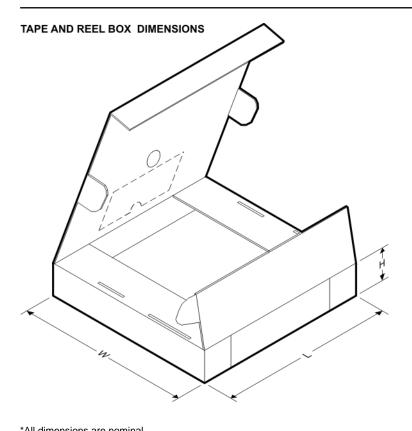
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC574DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74HC574DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74HC574DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74HC574NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1
SN74HC574PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
SN74HC574PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
SN74HC574PWRG4	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
SN74HC574PWT	TSSOP	PW	20	250	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

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PACKAGE MATERIALS INFORMATION

14-Jul-2012



*All dimensions are nominal							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC574DBR	SSOP	DB	20	2000	367.0	367.0	38.0
SN74HC574DWR	SOIC	DW	20	2000	366.0	364.0	50.0
SN74HC574DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74HC574NSR	SO	NS	20	2000	367.0	367.0	45.0
SN74HC574PWR	TSSOP	PW	20	2000	364.0	364.0	27.0
SN74HC574PWR	TSSOP	PW	20	2000	367.0	367.0	38.0
SN74HC574PWRG4	TSSOP	PW	20	2000	367.0	367.0	38.0
SN74HC574PWT	TSSOP	PW	20	250	367.0	367.0	38.0

J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within Mil-Std 1835 GDFP2-F20



LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N**) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AC.



LAND PATTERN DATA



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



NOTES:

A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994. β . This drawing is subject to change without notice.

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.

Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

E. Falls within JEDEC MO-153





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



MECHANICAL DATA

MSSO002E - JANUARY 1995 - REVISED DECEMBER 2001

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-150



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